



VMDSEMI

**VFTA010R077NA**

**Datasheet**



VMDSEMI

## General Description

## Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
100V	5.2mΩ@10V	87A

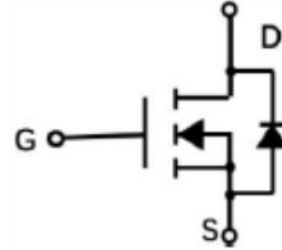


Figure 1 Symbol of VFTA010R077NA

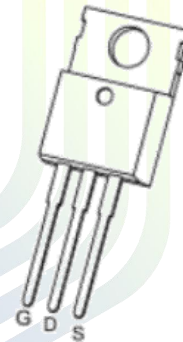
## Features

- Split Gate Trench Technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

## Application

- Industrial Power Supply
- Load Switch

## Package Type



**TO-220-3L**

Figure 2 Package Type of VFTA010R077NA

## Ordering Information

Product Name	Package
VFTA010R077NA	TO-220-3L

**Absolute Maximum Ratings** ( $T_A = 25\text{ °C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	100	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	87	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	350	
Avalanche Current <sup>Note3</sup>	$I_{AS}$	36	
Single Pulsed Avalanche Energy <sup>Note3</sup>	$E_{AS}$	324	mJ
Total Power Dissipation <sup>Note5</sup>	$P_D$	138	W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 to 150	°C

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note6</sup>	$R_{\theta JA}$		60		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		0.9		°C/W



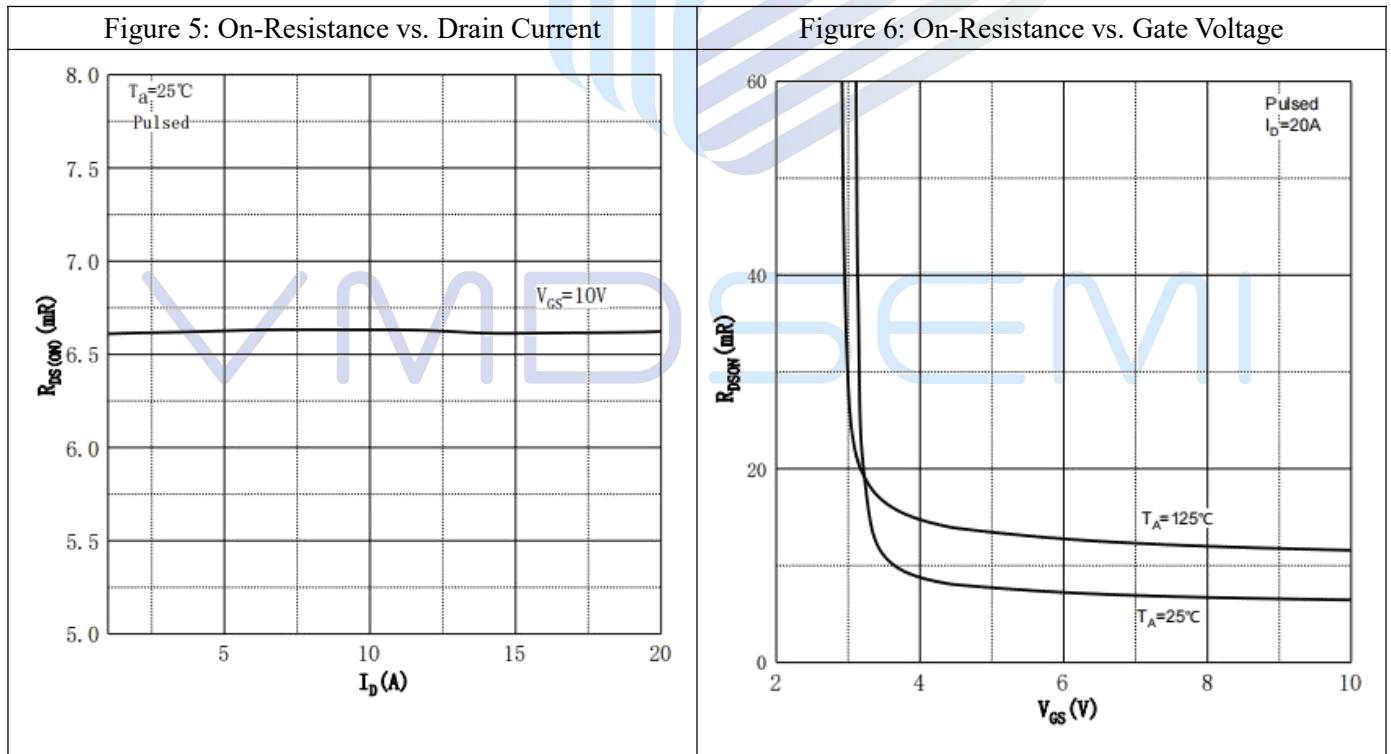
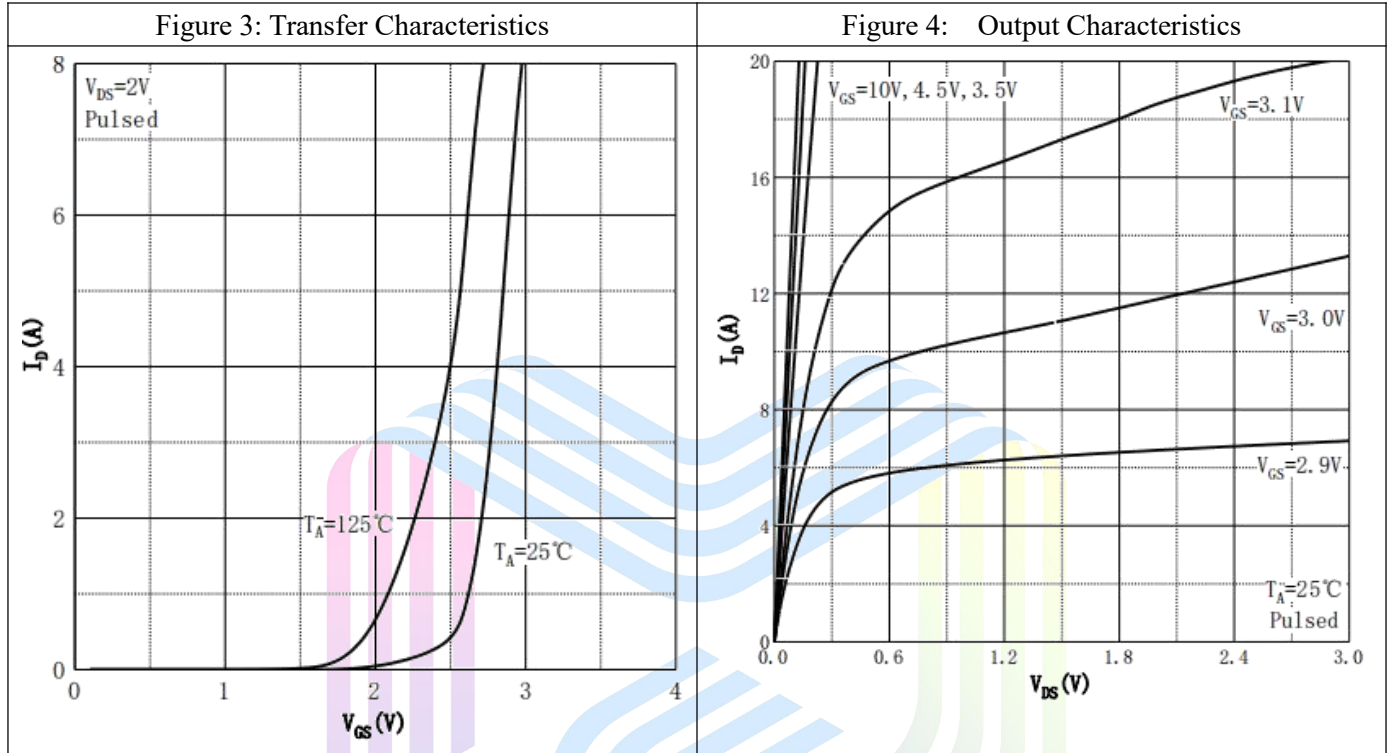
**Electrical Characteristics** ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

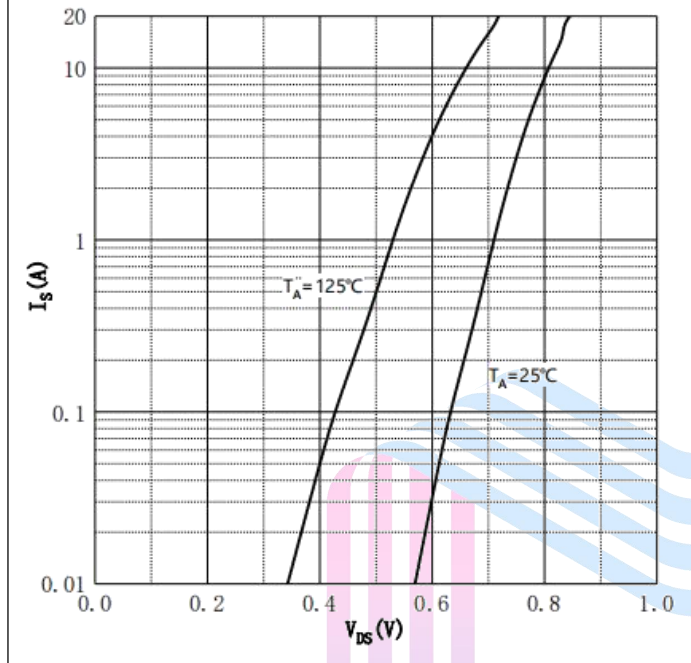
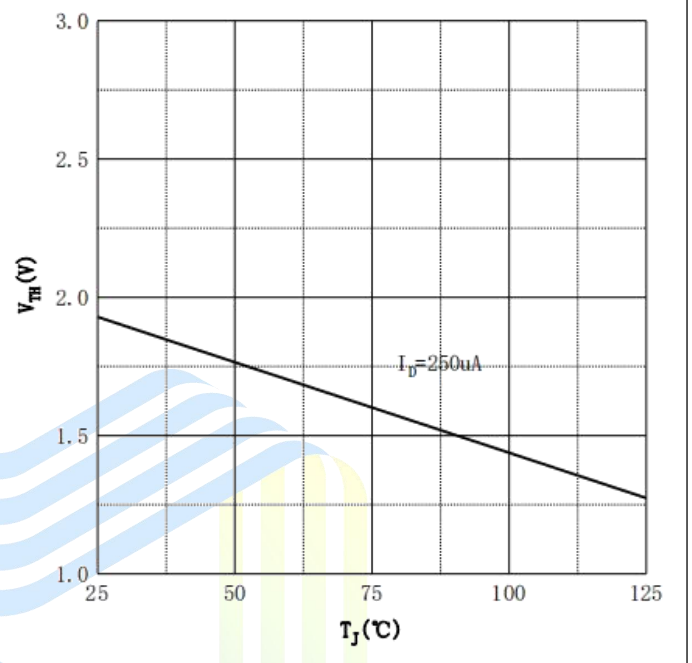
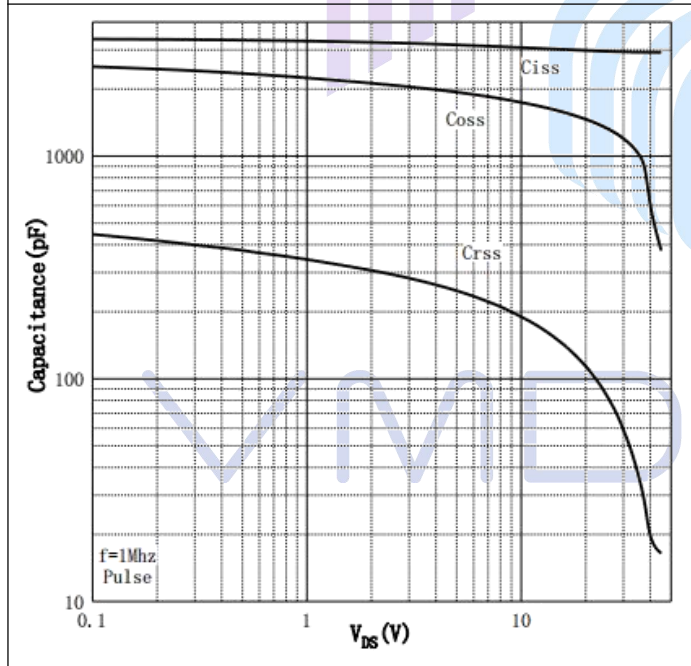
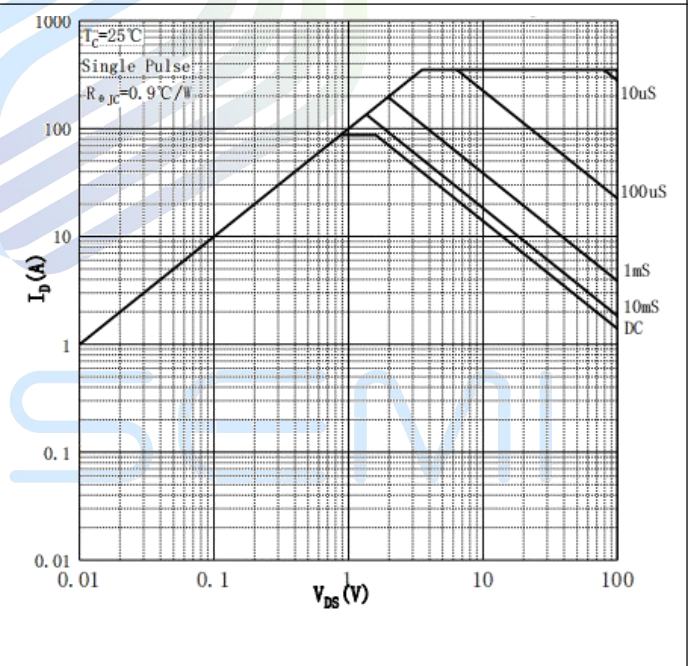
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$			1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note4</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	2	3	V
Static Drain-Source On-Resistance <sup>Note4</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$		6.7	7.7	mΩ
Forward Transconductance <sup>Note4</sup>	$g_{FS}$	$V_{DS}=10V, I_D=10A$		29		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=50V$		2915		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		370		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		16		pF
Total Gate Charge	$Q_g$	$V_{DS}=50V$		55		nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=10V$		18		
Gate-Drain Charge	$Q_{gd}$	$I_D=45A$		14		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$		1.2		Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$		15		ns
Turn-on Rise Time	$t_r$	$V_{GS}=10V$		10		
Turn-off Delay Time	$t_{d(off)}$	$R_L=1.2\Omega$		32		
Turn-off Fall Time	$t_f$	$R_G=3\Omega$		10		
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note4</sup>	$V_{SD}$	$V_{GS}=0V, I_S=10A$			1.2	V

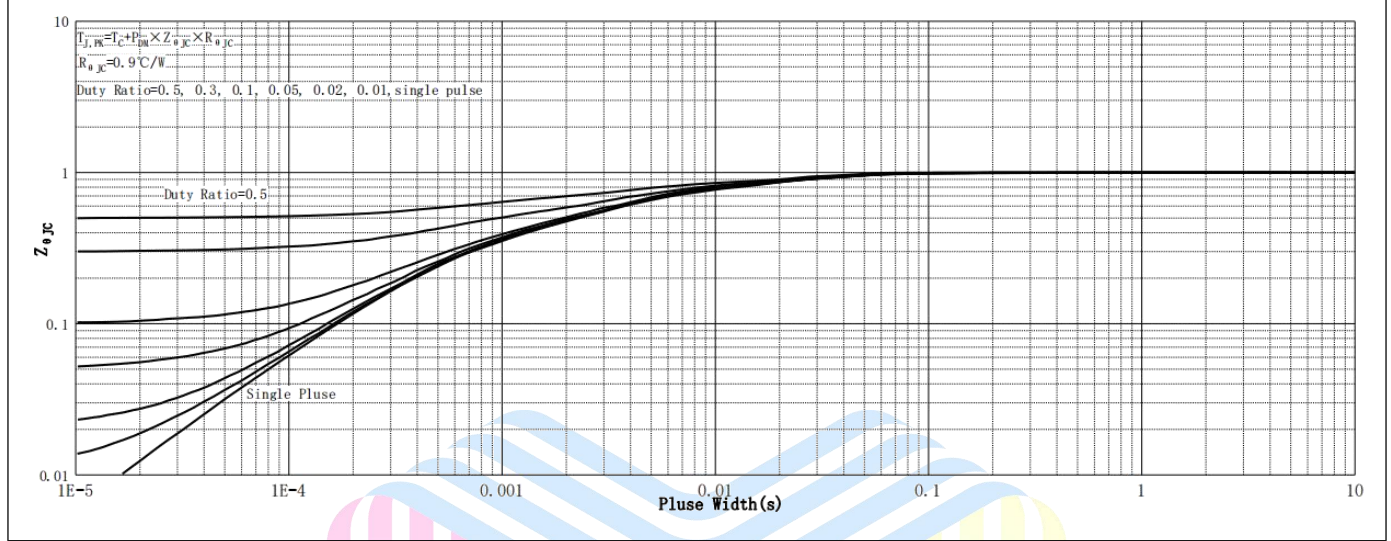
Notes :

- The maximum current rating is limited by package. And device mounted on a large heatsink.
- Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- $E_{AS}$  condition:  $V_{DD} = 50V, V_{GS} = 10V, L = 0.5mH, R_G=25\Omega$  Starting  $T_J = 25^\circ\text{C}$ .
- Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ . And device mounted on a large heatsink
- Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

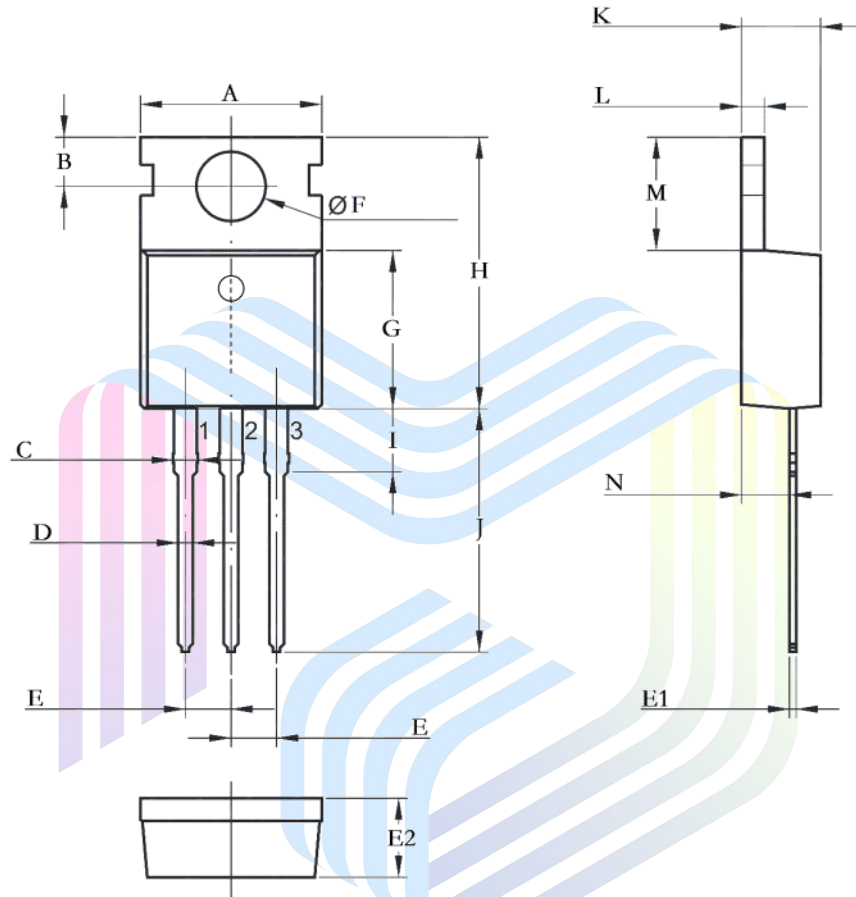
### Typical Performance Characteristics



**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**

**Figure 9: Typical Capacitance**

**Figure 10: Safe Operation Area**


**Figure 11: Normalized Maximum Transient Thermal Impedance**


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**Mechanical Dimensions:**
**TO-220-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.600	10.400	0.378	0.409
B	2.800TYP		0.110TYP	
C	1.200	1.600	0.047	0.063
D	0.600	1.000	0.024	0.039
E	2.540TYP		0.100TYP	
E1	0.300	0.700	0.012	0.028
E2	4.300	4.700	0.169	0.185
F	3.400	4.000	0.134	0.157
G	8.850	9.350	0.348	0.368
H	14.600	16.100	0.575	0.634
I	2.800	4.200	0.110	0.165
J	12.600	14.800	0.496	0.583
K	4.300	4.700	0.169	0.185
L	1.000	1.400	0.039	0.055
M	5.840	7.000	0.230	0.276
N	1.800	2.900	0.071	0.114



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